

U 101/76/30 with I 101/28/30 Cores

Series/Type: B67370

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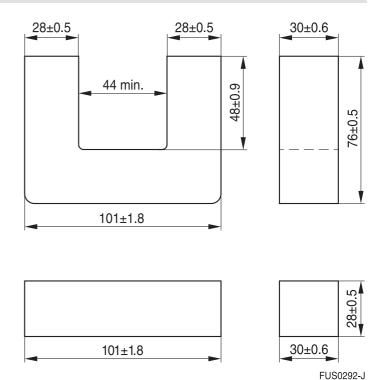
U 101/76/30 with I 101/28/30

Cores B67370

Delivery mode: single units

Magnetic characteristics (per set)

	UU 101/152/30	UI 101/104/30	
ΣΙ/Α	0.44	0.46	mm ⁻¹
l _e	368	258	mm
A_{e}	840	560	mm ²
A_{min}	840	560	mm ²
V_{e}	310800	144000	mm ³
m	1600	750	g/set



The A_L value in the table applies to a core set comprising two ungapped cores.

Material	A _L value nH	μ_{e}	P _V W/set	Ordering code
Combination 101/152/30				
N27	4600 +30/–20%	1580	< 16.5 (100 mT, 25 kHz, 100 °C)	B67370A0002X027
N87	5700 +30/–20%	1990	< 6.0 (100 mT, 25 kHz, 100 °C)	B67370A0002X187
N97	5900 +30/–20%	2060	< 4.2 (100 mT, 25 kHz, 100 °C)	B67370A0002X197
Combination 101/104/30				
N27	6700 +30/–20%	1750	< 12.0 (100 mT, 25 kHz, 100 °C)	B67370A0002X027 (U) B67370A0003X027 (I)

 A_L value is measured according to IEC 62044-2.

Visual inspection according to IEC 63093.



Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on AL value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement. To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the

customers' drilling process must be considered by increasing the hole diameter.



Cautions and warnings

Display of ordering codes for TDK Electronics products

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Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A _e	Effective magnetic cross section	mm ²
A_L	Inductance factor; $A_L = L/N^2$	nH
A _{L1}	Minimum inductance at defined high saturation ($\triangleq \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A _R	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega$ = 10 ⁻⁶ Ω
В	RMS value of magnetic flux density	Vs/m ² , mT
ΔΒ	Flux density deviation	Vs/m², mT
Ê	Peak value of magnetic flux density	Vs/m ² , mT
ΔÂ	Peak value of flux density deviation	Vs/m ² , mT
B _{DC}	DC magnetic flux density	Vs/m ² , mT
B _R	Remanent flux density	Vs/m ² , mT
B _S	Saturation magnetization	Vs/m ² , mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
Ea	Activation energy	J
f	Frequency	s ^{−1} , Hz
cutoff	Cut-off frequency	s ⁻¹ , Hz
max	Upper frequency limit	s ⁻¹ , Hz
min	Lower frequency limit	s ^{−1} , Hz
f _r	Resonance frequency	s ^{−1} , Hz
Cu	Copper filling factor	
g	Air gap	mm
Ⅎ	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_{DC}	DC field strength	A/m
H _c	Coercive field strength	A/m
n	Hysteresis coefficient of material	10 ⁻⁶ cm/A
า/µ¡²	Relative hysteresis coefficient	10 ⁻⁶ cm/A
	RMS value of current	Α
DC	Direct current	Α
	Peak value of current	A
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
K 3	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Cautions and warnings

Symbol	Meaning	Unit
$\Delta L/L$	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L_H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L _s	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P_{trans}	Transferrable power	W
P_V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = ω L/R _s = 1/tan δ _L)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R_h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R_i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s	Series loss resistance of a core	Ω
R_{th}	Thermal resistance	K/W
R_V	Effective loss resistance of a core	Ω
S	Total air gap	mm
Т	Temperature	°C
ΔT	Temperature difference	K
T _C	Curie temperature	°C
t	Time	S
t _v	Pulse duty factor	
tan δ	Loss factor of coil	
tan δ _L	Loss factor of coil	
tan δ_r	(Residual) loss factor at $H \rightarrow 0$ Relative loss factor	
tan δ_e		
tan δ_h	Hysteresis loss factor	
tan δ/μ _i	Relative loss factor of material at $H \rightarrow 0$	
Û	RMS value of voltage	V
Û	Peak value of voltage	V
V _e	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z_n	Normalized impedance $ Z _n = Z / N^2 \times \varepsilon (I_e / A_e)$	Ω /mm



Cautions and warnings

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α_{e}	Temperature coefficient of effective permeability	1/K
ϵ_{r}	Relative permittivity	
Φ	Magnetic flux	Vs
η	Efficiency of a transformer	
η_{B}	Hysteresis material constant	mT-1
η_{i}	Hysteresis core constant	$A^{-1}H^{-1/2}$
λ_{s}	Magnetostriction at saturation magnetization	
μ	Relative complex permeability	
μ_0	Magnetic field constant	Vs/Am
μ_{a}	Relative amplitude permeability	
μ_{app}	Relative apparent permeability	
μ_{e}	Relative effective permeability	
μ_{i}	Relative initial permeability	
μ_p '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
μ _p "	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
μ_{r}	Relative permeability	
$\mu_{\sf rev}$	Relative reversible permeability	
μ_s '	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
μ_s "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
μ_{tot}	Relative total permeability derived from the static magnetization curve	
ρ	Resistivity	Ω m $^{-1}$
ΣΙ/Α	Magnetic form factor	mm ⁻¹
τ_{Cu}	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
ω	Angular frequency; ω = 2 Π f	s ⁻¹

Note:

All dimensions are given in mm.



Surface-mount device



The following applies to all products named in this publication:

- Some parts of this publication contain statements about the suitability of our products for certain areas of application. These statements are based on our knowledge of typical requirements that are often placed on our products in the areas of application concerned. We nevertheless expressly point out that such statements cannot be regarded as binding statements about the suitability of our products for a particular customer application. As a rule we are either unfamiliar with individual customer applications or less familiar with them than the customers themselves. For these reasons, it is always ultimately incumbent on the customer to check and decide whether a product with the properties described in the product specification is suitable for use in a particular customer application.
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- The warnings, cautions and product-specific notes must be observed.
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Importanat notes

8 The trade names EPCOS, CarXield, CeraCharge, CeraDiode, CeraLink, CeraPad, CeraPlas, CSMP, CTVS, DeltaCap, DigiSiMic, FilterCap, FormFit, InsuGate, LeaXield, MediPlas, MiniBlue, MiniCell, MKD, MKK, ModCap, MotorCap, PCC, PhaseCap, PhaseCube, PhaseMod, PhiCap, PiezoBrush, PlasmaBrush, PowerHap, PQSine, PQvar, SIFERRIT, SIFI, SIKOREL, SilverCap, SIMDAD, SiMic, SIMID, SineFormer, SIOV, SurfIND, ThermoFuse, WindCap, XieldCap are trademarks registered or pending in Europe and in other countries. Further information will be found on the Internet at www.tdkelectronics.tdk.com/trademarks.

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